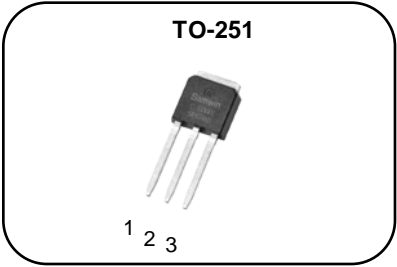


N-channel Enhancement mode TO-251 MOSFET

Features

- High ruggedness
- $R_{DS(ON)}$ (Typ 4.9mΩ) @ $V_{GS}=10V$
- Gate Charge (Typ 62.3nC)
- Improved dv/dt Capability
- 100% Avalanche Tested
- Application:DC-DC, Motor Control



1. Gate 2. Drain 3. Source

BV_{DSS} : 30V
 I_D : 85A
 $R_{DS(ON)}$: 4.9mΩ



General Description

This power MOSFET is produced with advanced technology of SAMWIN. This technology enable power MOSFET to have better characteristics, such as fast switching time, low on resistance, low gate charge and especially excellent avalanche characteristics.

Order Codes

Item	Sales Type	Marking	Package	Packaging
1	SW I 85N03C	SW85N03C	TO-251	TUBE

Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DSS}	Drain to Source Voltage	30	V
I_D	Continuous Drain Current (@ $T_C=25^{\circ}C$)	85*	A
	Continuous Drain Current (@ $T_C=100^{\circ}C$)	53.5*	A
I_{DM}	Drain current pulsed (note 1)	340	A
V_{GS}	Gate to Source Voltage	± 20	V
E_{AS}	Single pulsed Avalanche Energy (note 2)	195	mJ
E_{AR}	Repetitive Avalanche Energy (note 1)	20	mJ
dv/dt	Peak diode Recovery dv/dt (note 3)	5	V/ns
P_D	Total power dissipation (@ $T_C=25^{\circ}C$)	89	W
	Derating Factor above 25°C	0.7	W/°C
T_{STG}, T_J	Operating Junction Temperature & Storage Temperature	-55 ~ + 150	°C
T_L	Maximum Lead Temperature for soldering purpose, 1/8 from Case for 5 seconds.	300	°C

*. Drain current is limited by junction temperature.

Thermal characteristics

Symbol	Parameter	Value	Unit
R_{thjc}	Thermal resistance, Junction to case	1.4	°C/W
R_{thcs}	Thermal resistance, Case to Sink	0.5	°C/W
R_{thja}	Thermal resistance, Junction to ambient	80	°C/W

Electrical characteristic ($T_C = 25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Off characteristics						
BV_{DSS}	Drain to source breakdown voltage	$V_{GS}=0V, I_D=250\mu A$	30			V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown voltage temperature coefficient	$I_D=250\mu A$, referenced to 25°C		0.01		$V/^{\circ}\text{C}$
I_{DSS}	Drain to source leakage current	$V_{DS}=30V, V_{GS}=0V$			1	μA
		$V_{DS}=24V, T_C=125^{\circ}\text{C}$			50	μA
I_{GSS}	Gate to source leakage current, forward	$V_{GS}=20V, V_{DS}=0V$			100	nA
	Gate to source leakage current, reverse	$V_{GS}=-20V, V_{DS}=0V$			-100	nA
On characteristics						
$V_{GS(TH)}$	Gate threshold voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2		2.4	V
$R_{DS(ON)}$	Drain to source on state resistance	$V_{GS}=10V, I_D=40A$		4.9	5.8	m Ω
G_{fs}	Forward Transconductance	$V_{DS}=8V, I_D=40A$		82		S
Dynamic characteristics						
C_{iss}	Input capacitance	$V_{GS}=0V, V_{DS}=25V, f=1\text{MHz}$		2986		pF
C_{oss}	Output capacitance			326		
C_{rss}	Reverse transfer capacitance			320		
$t_{d(on)}$	Turn on delay time	$V_{DS}=15V, I_D=14A, R_G=25\Omega$ (note 4 , 5)		14		nS
t_r	Rising time			59		
$t_{d(off)}$	Turn off delay time			193		
t_f	Fall time			96		
Q_g	Total gate charge	$V_{DS}=25V, V_{GS}=10V, I_D=14A$ (note 4 , 5)		62		nC
Q_{gs}	Gate-source charge			8		
Q_{gd}	Gate-drain charge			18		

Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_S	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			85	A
I_{SM}	Pulsed source current				340	A
V_{SD}	Diode forward voltage drop.	$I_S=20A, V_{GS}=0V$			1.4	V
T_{rr}	Reverse recovery time	$I_S=14A, V_{GS}=0V,$		15.5		nS
Q_{rr}	Breakdown voltage charge	$di/dt=100A/\mu s$		5.5		nC

※. Notes

1. Repetitive rating : pulse width limited by junction temperature.
2. $L=0.4\text{mH}, I_{AS}=30A, V_{DD}=20V, R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$
3. $I_{SD} \leq 14A, di/dt = 100A/\mu s, V_{DD} \leq BV_{DSS}$, Starting $T_J=25^{\circ}\text{C}$
4. Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$
5. Essentially independent of operating temperature.

Fig. 1. On-state characteristics

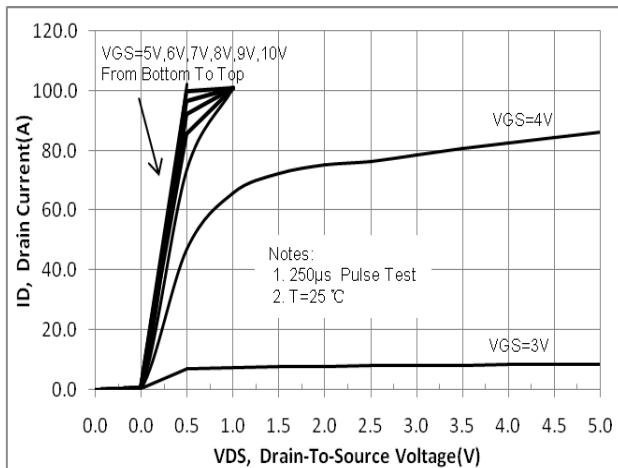


Fig. 2. On-resistance variation vs. drain current and gate voltage

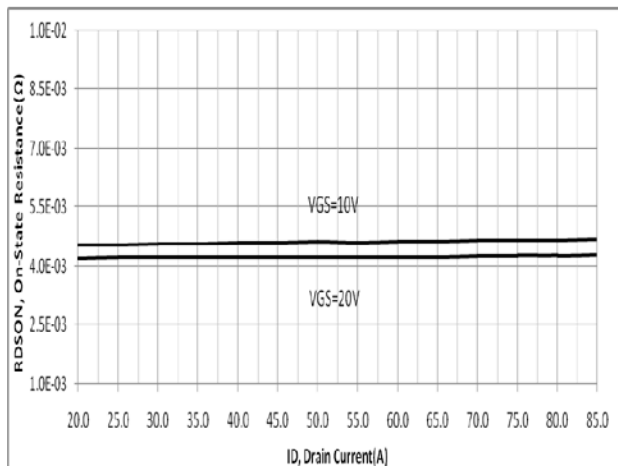


Fig. 3. Gate charge characteristics

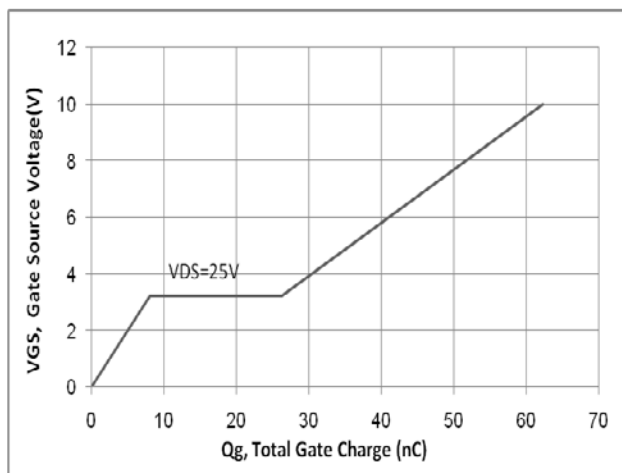


Fig. 4. On state current vs. diode forward voltage

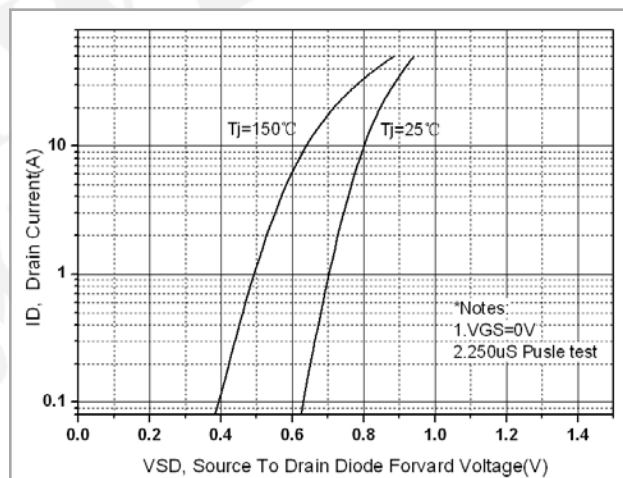


Fig 5. Breakdown Voltage Variation vs. Junction Temperature

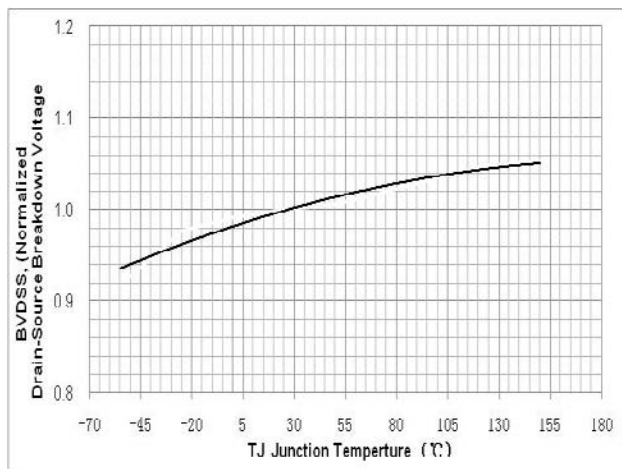


Fig. 6. On resistance variation vs. junction temperature

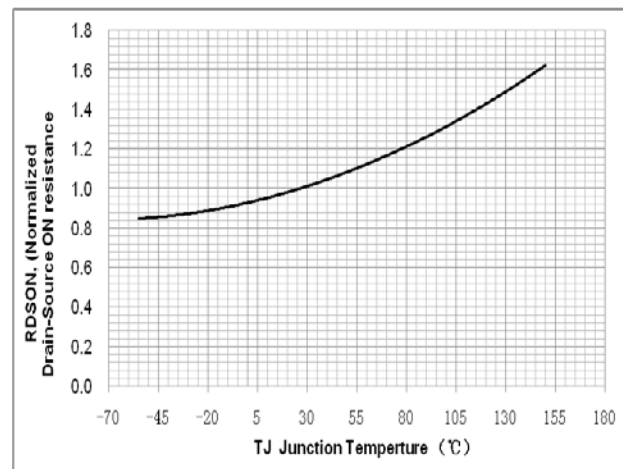


Fig. 7. Maximum safe operating area

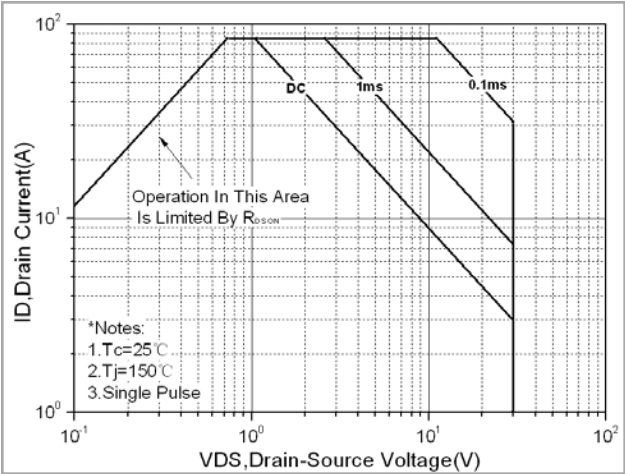


Fig. 8. Transient thermal response curve

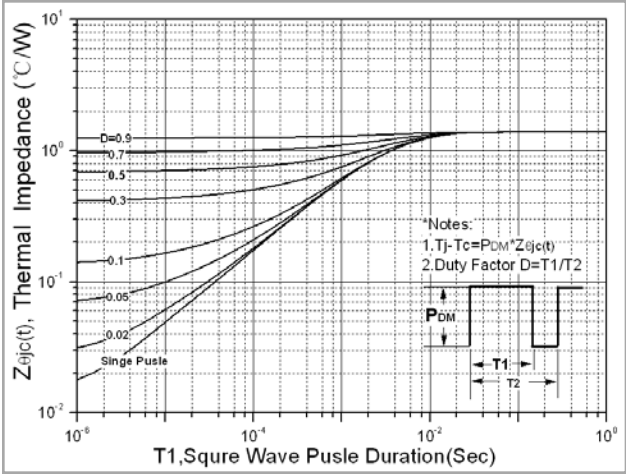


Fig. 9. Capacitance Characteristics

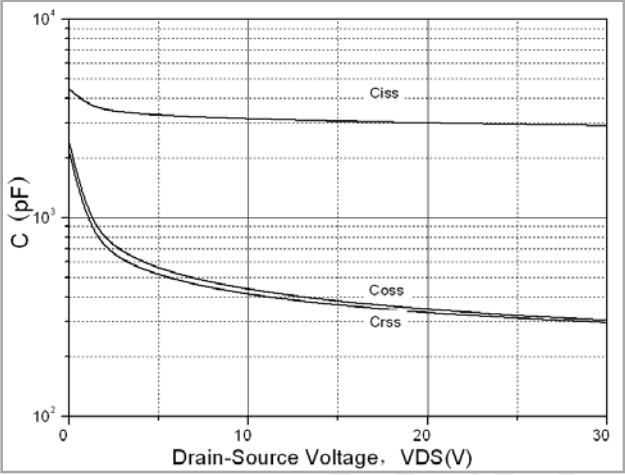


Fig. 10. Gate charge test circuit & waveform

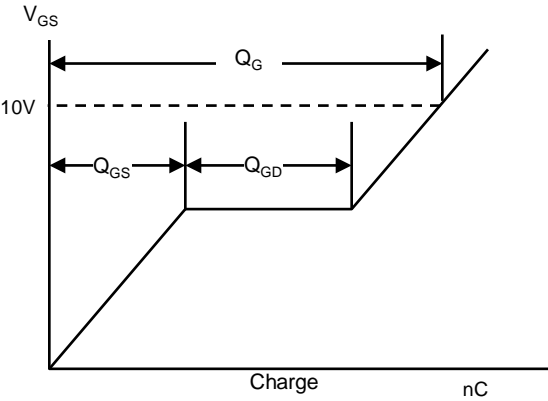
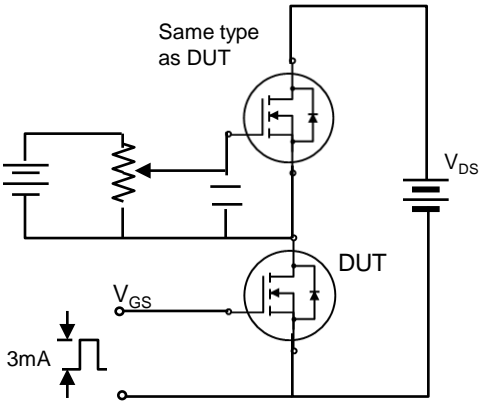


Fig. 11. Switching time test circuit & waveform

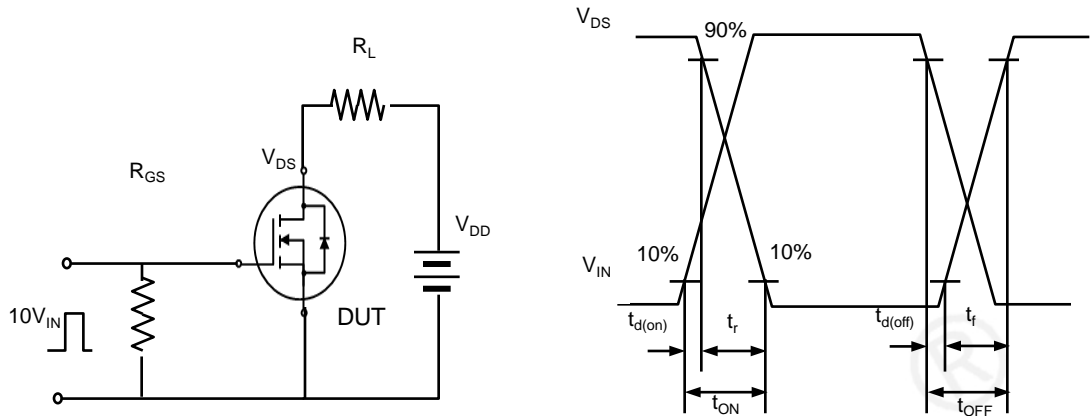


Fig. 12. Unclamped Inductive switching test circuit & waveform

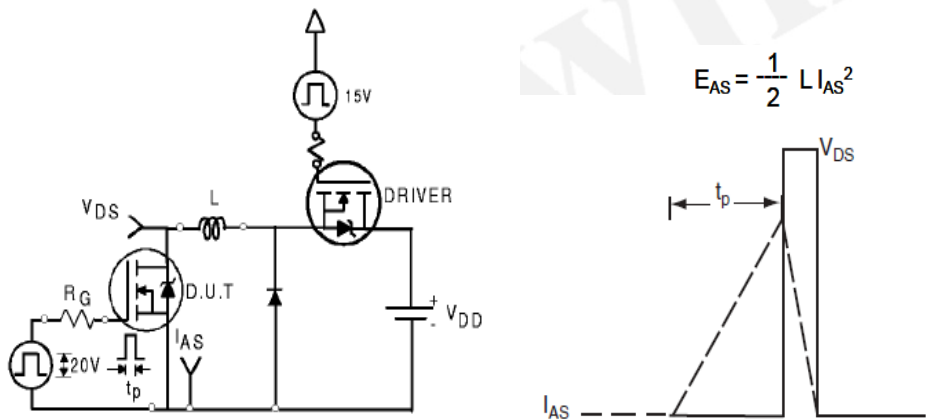
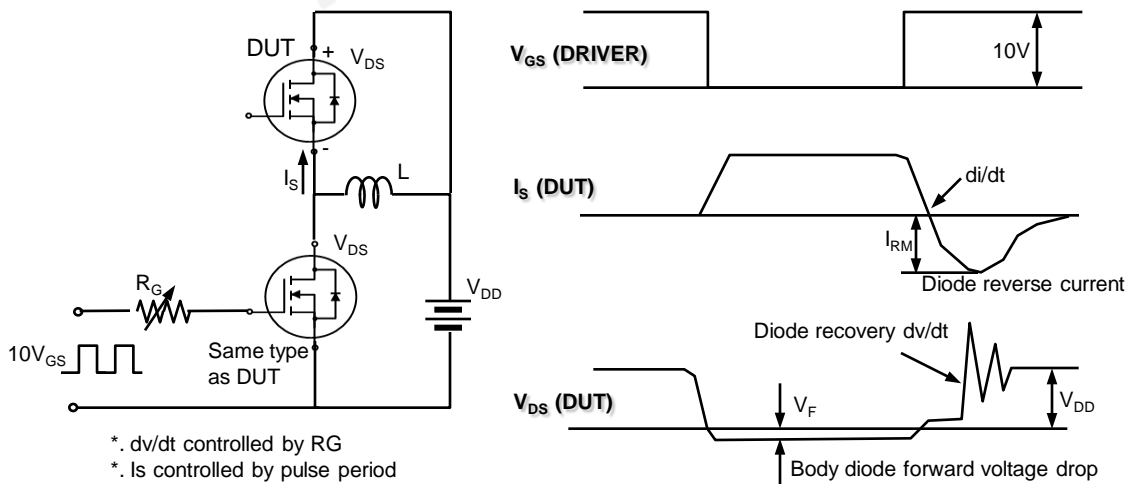



Fig. 13. Peak diode recovery dv/dt test circuit & waveform



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DISCLAIRATION:

- * All the data&curve within this document was tested in XI'AN SEMIPOWER TESTING&APPLICATION CENTER.
- * This product has passed the PCT,TC,HTRB,HTGB,HAST,PC and Solderdunk reliability testing.
- * Qualification Standards can also be found on the Web site (<http://www.semipower.com.cn>) 
- * Any advice, please send your proposal to samwin@samwinsemi.com